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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Neo C. Peng et al.

Title: WAFER DICING DEVICE AND METHOD

Docket No.: 303.772US2

Filed: April 13, 2004

Examiner: Unknown

Serial No.: 10/823,314

Due Date: N/A

Group Art Unit: 1725

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the attached:

☒ Communication Re: Incorrect Filing Receipt (1 pg.)

☒ Copy of Filing Receipt (2 pgs.)

☒ Copy of Declaration filed with Application along with copy of returned postcard (5 pgs.).

☒ A return postcard.

No Additional fee is required.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer No: 21186

By: 

Name: Timothy B Clise

Reg. No. 40,957

TBC:CMG:ker

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 20 day of July, 2004.


Name


Signature



SAN 10/823,314

PATENT

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Applicant: Neo C. Peng et al.

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Customer No. 21186

Confirmation No. 4743

Title: WAFER DICING DEVICE AND METHOD

COMMUNICATION RE: INCORRECT FILING RECEIPT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants hereby request correction of the Filing Receipt with respect to the above-identified patent application. In the Filing Receipt received June 29, 2004, (copy enclosed), the Filing Receipt Reads: Chew Beng Chyt. The Filing Receipt should read: Chew Beng Chye.

Applicants would appreciate the above-identified printing error be corrected and that a new "corrected" filing receipt be sent to Applicants' representatives at the address given below.

Respectfully submitted,

NEO C. PENG ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9587

Date

20 July '04

By

Timothy B. Clise
Reg. No. 40,957
TBC:CMG:ker

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Name

Kyrstin Ryan

Signature

Kyrsti Ryan



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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/823,314	04/13/2004	1725	856	303.772US2	6	20	4

CONFIRMATION NO. 4743

21186

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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FILING RECEIPT



OC000000013065628

Date Mailed: 06/25/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Neo Chee Peng, Singapore, SINGAPORE;
 Kian Shing Tan, Singapore, SINGAPORE;
 Chew Beng Chyt, Singapore, SINGAPORE;
 Tan Hock Chuan, Singapore, SINGAPORE;
 Fong Chun Wai, Singapore, SINGAPORE;

Assignment For Published Patent Application

Micron Technology, Inc.;

Domestic Priority data as claimed by applicant

This application is a DIV of 10/118,666 07/09/2002 PAT 6,737,606

Foreign Applications

SINGAPORE 200105517-7 09/10/2001

If Required, Foreign Filing License Granted: 06/24/2004

Projected Publication Date: 09/30/2004

Non-Publication Request: No

Early Publication Request: No

PORTFOLIO I.P.

JUN 29 2004

RECEIVED

Title

Wafer dicing device and method

Preliminary Class

219

**LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

GRANTED

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22141 U.S. PTO
10/823314



041304

DIV

In re Patent Application of: Neo C. Peng et al.
Title: WAFER DICING DEVICE AND METHOD
Attorney Docket No.: 303.772US2

Receipt is hereby acknowledged for the following in the United States Patent and Trademark Office:

CONTENTS: (DIVISIONAL) :Specification (21 pgs, including claims numbered 1 through 20 and a 1 page Abstract); Formal Drawing(s) (6 sheets); Copy of signed Declaration (4 pgs) from prior application; Copy of Power of Attorney from prior application (1 pg); Check in the amount of \$856.00 to pay the filing fee; Information Disclosure Statement (2 pgs), Form 1449 (2 pgs); return postcard and transmittal sheet.

EXPRESS MAIL LABEL NO. EV299683348US

Mailed: April 13, 2004

TBC/tmk



SCHWEOMAN ■ LUNDBERG ■ WOESSNER ■ KLUTH

DECLARATION FOR PATENT APPLICATION

As a below named inventor I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first or joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

WAFER DICING DEVICE AND METHOD .

The specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56 (see page 4 attached hereto).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on the basis of which priority is claimed:

Foreign application(s), if any, claiming priority under 35 U.S.C. § 119:

Application Number
200105517-7

Country
Singapore

Month/Day/Year Filed
09/10/2001

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

No such claim for priority is being made at this time.

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT International application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT International filing date of this application.

No such claim for priority is being made at this time.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of joint inventor number 1: Neo Chee Peng

Citizenship: Singapore

Residence: Singapore, Singapore

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#07-270

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Signature: _____

Neo Chee Peng

Date: _____

3/19/02

Full Name of joint inventor number 2: Kian Shing Tan

Citizenship: Singapore

Residence: Singapore, Singapore

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Singapore S30449

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Signature: _____

Kian Shing Tan

Date: _____

3/18/02

Full Name of joint inventor number 3: Chew Beng Chye

Citizenship: Singapore

Residence: Singapore, Singapore

Post Office Address: Blk 106 Teck Whye Lane

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Signature: _____

Chew Beng Chye

Date: _____

3/18/02

Full Name of joint inventor number 4: Tan Hock Chuan

Citizenship: Singapore

Residence: Singapore, Singapore

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Singapore S1059

Singapore

Signature: _____

Tan Hock Chuan

Date: _____

3/18/02

X Additional inventors are being named on separately numbered sheets, attached hereto.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of joint inventor number 5: Fong Chun Wai

Citizenship: Singapore

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Signature: _____

Fong Chun Wai

Date: _____

15 March 2002

Full Name of inventor: _____

Citizenship: _____

Residence: _____

Post Office Address: _____

Signature: _____

Date: _____

Full Name of inventor: _____

Citizenship: _____

Residence: _____

Post Office Address: _____

Signature: _____

Date: _____

Full Name of inventor: _____

Citizenship: _____

Residence: _____

Post Office Address: _____

Signature: _____

Date: _____

§ 1.56 Duty to disclose information material to patentability.

(a) A patent by its very nature is affected with a public interest. The public interest is best served, and the most effective patent examination occurs when, at the time an application is being examined, the Office is aware of and evaluates the teachings of all information material to patentability. Each individual associated with the filing and prosecution of a patent application has a duty of candor and good faith in dealing with the Office, which includes a duty to disclose to the Office all information known to that individual to be material to patentability as defined in this section. The duty to disclose information exists with respect to each pending claim until the claim is canceled or withdrawn from consideration, or the application becomes abandoned. Information material to the patentability of a claim that is canceled or withdrawn from consideration need not be submitted if the information is not material to the patentability of any claim remaining under consideration in the application. There is no duty to submit information which is not material to the patentability of any existing claim. The duty to disclose all information known to be material to patentability is deemed to be satisfied if all information known to be material to patentability of any claim issued in a patent was cited by the Office or submitted to the Office in the manner prescribed by §§ 1.97(b)-(d) and 1.98. However, no patent will be granted on an application in connection with which fraud on the Office was practiced or attempted or the duty of disclosure was violated through bad faith or intentional misconduct. The Office encourages applicants to carefully examine:

- (1) prior art cited in search reports of a foreign patent office in a counterpart application, and
- (2) the closest information over which individuals associated with the filing or prosecution of a patent application believe any pending claim patentably defines, to make sure that any material information contained therein is disclosed to the Office.

(b) Under this section, information is material to patentability when it is not cumulative to information already of record or being made of record in the application, and

- (1) it establishes, by itself or in combination with other information, a prima facie case of unpatentability of a claim; or
- (2) it refutes, or is inconsistent with, a position the applicant takes in:
 - (i) opposing an argument of unpatentability relied on by the Office, or
 - (ii) asserting an argument of patentability.

A prima facie case of unpatentability is established when the information compels a conclusion that a claim is unpatentable under the preponderance of evidence, burden-of-proof standard, giving each term in the claim its broadest reasonable construction consistent with the specification, and before any consideration is given to evidence which may be submitted in an attempt to establish a contrary conclusion of patentability.

(c) Individuals associated with the filing or prosecution of a patent application within the meaning of this section are:

- (1) Each inventor named in the application;
- (2) Each attorney or agent who prepares or prosecutes the application; and
- (3) Every other person who is substantively involved in the preparation or prosecution of the application and who is associated with the inventor, with the assignee or with anyone to whom there is an obligation to assign the application.

(d) Individuals other than the attorney, agent or inventor may comply with this section by disclosing information to the attorney, agent, or inventor.